CLAIMS

1. A release sheet for semiconductor compression molding, the release sheet comprising:

a release layer comprising particles; and

a base layer,

wherein a content ratio of the particles in the release layer is from 5% by volume to 65% by volume, and

wherein the particles comprise resin particles.

2. The release sheet for semiconductor compression molding according to claim 1, wherein the particles have an average particle diameter of from 1 μm to 55 μm.

3. The release sheet for semiconductor compression molding according to claim 1 or 2, wherein the resin particles comprise at least one selected from the group consisting of an acrylic resin, a polyolefin resin, a polystyrene resin, a polyacrylonitrile resin, and a silicone resin.

4. The release sheet for semiconductor compression molding according to any one of claims 1 to 3, wherein the base layer comprises a polyester film.

5. A semiconductor package molded using the release sheet for semiconductor compression molding according to any one of claims 1 to 4.